

Day 1 - Monday 7th April 2025

18:00 Pre-conference networking drinks reception

Day 2 - Tuesday 8th April 2025

08:00 Registration and welcome refreshments

08:50 Housekeeping by Michael Lebbby and David Cheskis - Conference Chairs

Optimising materials and architectures to progress PICs

09:00 **Germanium Electro-Absorption Modulators: Fast, Compact and Energy-efficient**

Presented by Daniel Steckler - IHP Microelectronics

09:15 **UV Photonics and Rare-earth Doped Amplifiers with Sputter-deposited Aluminium Oxide Waveguides**

Presented by Dawson Bonneville - University of Twente

09:30 **Two-Photon Grayscale Lithography: An Enabling Technology for Scalable Fabrication of Aligned Micro-Optics**

Presented by Tobias Hoose - Nanoscribe

09:45 **IMEC's Agile Photonics Platforms**

Presented by Leili Shiramin - imec

10:00 **Photonic Integrated Circuit Packaging**

Presented by Liam Moroney - Alter Technology

10:15 Morning Break

10:55 **Comparing PIC Platforms: What's the Best Fit?**

Presented by Sam Dale - IDTechEx

11:10 **Structuring and Uniformity Improvement of Thin Film LN and other Waveguide Materials**

Presented by Philipp Böttger - scia Systems GmbH

11:25 **Advancing towards 50G PON with Flexible Multi-Tech PICs**

Presented by Antonio Teixeira - PICadvanced

11:40 **Industry Ready Photonic Integration using Photonic Wire Bonds & Facet-Attached Micro-Lenses**

Presented by Matthias Lauermaun - Vanguard Automation

11:55 **The Future Role of Bonding in Photonic Integrated Circuits and Co-Packaged Optics**

Presented by Dr. Bernd Dielacher - EV Group

12:10 Lunch Break

Delivering more data: AI, machine learning and tomorrow's computing

Sponsored by OPTICA

13:40 **The Evolving Role of Optics in AI Clusters**

Presented by Vlad Kozlov - LightCounting

13:55 **Integrated Neuromorphic Photonics and Optical Computing Accelerators**

Presented by Mat?j Hejda - Hewlett Packard Enterprise

14:10 **Accelerating Photonic Design for Next Generation Computing with Multiphysics Simulation**

Presented by Dylan McGuire - Ansys

14:25 **Driving Functional Test Closer to the Chip**

Presented by Matt Adams - VIAVI Solutions

14:40 **Serving Reliable and Robust Test and Measurement Needs**

Presented by Kazuo Yamaguchi - Keysight Technologies

14:55 **Custom PDK Framework for PIC Design and Simulation of Datacenter Interconnects**

Presented by Andrzej Po?atynski - VPIphotonics

15:10 Afternoon Break

15:50 **Optical Interconnects for Next Generation of AI Systems**

Presented by Ana González - iPronics

16:05 **Modular System Concepts for Photonics Packaging and Testing**

Presented by Andon Bano - ficonTEC

16:20 **Breaking the Bottleneck: High-Volume Manufacturing of TFLN PICs for Telecom & Datacom**

Presented by Amir Ghadimi - Lightium

16:35 **The Future of Optical Interconnects is 3D Printed Freeform Optics**

Presented by Dr. Laura Horan - Vanguard Automation

16:50 **Bridging the gap between PIC Designer and Foundries**

Presented by Martin Fiers - Luceda Photonics

17:05 **Thin film lithium niobate: the ideal material for scalable high-performance photonic components and PICs**

Presented by Pouya Dianat - Quantum Computing

17:20 **Merging Photonic Design and Test Towards Scalable Product Development**

Presented by Iñigo Artundo - VLC Photonics

17:35 Closing Remarks

18:00 Networking Drinks / Dinner Reception

Day 3 - Wednesday 9th April 2025

08:00 Registration and welcome refreshments

08:50 Housekeeping by Michael Lebby and David Cheskis - Conference Chairs

Optimising materials and architectures to progress PICs

09:00 **Advancing TFLN PICs to Meet Market Demand and Scale Production**
Presented by Hamed Sattari - CCRAFT

09:15 **Enabling Increasingly Dense fiber-to-chip Connections in Datacenters**
Presented by Benoit Fleury - Corning

09:30 **InP PIC Platform and Architectures for Data-Center Applications**
Presented by Mehrdad Ziari - Nokia

09:45 **What about the PIC Manufacturing Sweet Spot?**
Presented by Twan Korthorst - New Origin

10:00 **Advanced Photonic Integrated Circuit Testing: APEX Technologies' Solution for Next-Generation Optical Devices**
Presented by Marc-Andre Laliberte - APEX Technologies

10:15 Morning Break

10:55 **Leveraging Opportunity: Test and Assembly as Fulcrum for Scaling**
Presented by Scott Jordan - Physik Instrumente

11:10 **Sputtered Thin-Film Aluminum Nitride on Insulator for Integrated Photonics: a Scalable Approach and Application Potential**
Presented by Thang Duy Dao - Silicon Austria Labs (SAL)

11:25 **Accelerating the Adoption of Advanced Photonic Integrated Circuits Using Design Standardisation in PIC Packaging**
ficonTEC, PHIX, imec, and Photonics Foundry

11:55 Lunch Break

Harnessing PICs in healthcare, autonomous vehicles and beyond

Sponsored by PhotonDelta

13:25 **Scaling up LiDAR with Silicon Photonics**
Presented by François Simoens - SteerLight

13:40 **Aluminum Oxide PICs for UV Microscopy and Sensing**
Presented by Nicolas Le Thomas - Ghent University

13:55 **The Future of PICs in Agrifood, Healthcare & Industrial Sensing**
Presented by Peter van Arkel - PhotonDelta

14:10 **Silicon Photonics for Enabling Chip-based Solid-state Automotive FMCW LiDAR**
Presented by Marcus Dahlem - imec

14:25 **SiN PICs for Optical Coherence Tomography**
Presented by Rainer Hainberger - AIT Austrian Institute of Technology GmbH

14:40 **Industrial BioChemical Detection with On-chip Raman Technology**
Presented by Ivan-Lazar Bundalo - InSpek

14:55 Afternoon Break

Advancing quantum 2.0 technologies with PICs

15:35 **Advancing Quantum Communications with PICs**
Presented by Taofiq K. Paraiso - Toshiba Europe Limited

15:50 **How Photonics Can Support Quantum Innovation in Different Applications**
Presented by Eric Mounier - Yole Group

16:05 **Modular, Fibre-Interconnected Architectures for Photonic Quantum Computers**
Presented by Thien-An Nguyen - Orca Computing

16:20 Closing Remarks

